

Video Accessory IC Series

For portable image equipment Upscaler IC

BU1521GVW



No.09069EAT02

- Description

BU1521GVW upscales and interpolates images when upconverting to the HDTV (Maximum 1080P) format from the usual SDTV (NTSC/PAL) format.

High quality IP change · up scale management is realized by the frame memory less operate.

It is the LSI which is the most suitable for the compact system of the mobile.

- Features

- 1) Input format

480i or 576i(ITUR BT656) YCbCr 4:2:2(ITUR BT601) 8bit Digital Interface

- 2) Output Format

480i or 576i(ITUR BT656) YCbCr 4:2:2 8bit Digital Interface

480p or 576p(SMPTE 293 · ITUR BT1358) YCbCr 4:2:2 16bit Digital Interface

1080/59.94i(SMPTE 274) YCbCr 4:2:2 16bit Digital Interface

1080/50i(SMPTE 274) YCbCr 4:2:2 16bit Digital Interface

1080/59.94p(SMPTE 274) YCbCr 4:2:2 16bit Digital Interface

1080/50p(SMPTE 274) YCbCr 4:2:2 16bit Digital Interface

- 3) IP conversion function

Conversion function from interlace to progressive

- 4) Upscale function

Horizontal direction: 720 pixels pass-through or upscaling to 1920 pixels

Vertical direction: up scaling to 480, 576, 540, and 1080 pixels

- 5) Filter function

5 × 5 filtering function over input data

Filter coefficient is programmable with registers

- 6) Register access

Register read/write through the SPI interface

Burst write/read support

- 7) Built-in PLL

Input frequency 27MHz

Output frequency 74.25MHz, 74.175824MHz, 148.5MHz, 148.351648MHz

- 8) Power-down mode and through-mode support

Power-down mode can be controlled through STBY pin or register setting.

Through-mode can be selected by register setting.

- 9) Supply voltage

VDD(core voltage) 1.15V~1.25V、AVDD(PLL)=2.7V~3.3V、

VDDIO1(SDTV input)=1.7V~3.6V、VDDIO2(control)=2.7V~3.3V、

VDDIO3(HDTV output)=1.7V~1.9V

- 10) Package

63 pin, BGA package (SBGA063W060, Size = 6 mm × 6 mm, 0.65 mm pitch)

- Applications

Digital Video Camera, Digital still camera, Video game, a portable DVD

● Absolute Maximum Rating

Table. 1 Absolute maximum rating

| Parameter | Symbol | Rating | Unit |
|------------------------------|--------|-----------------|------|
| Supply voltage 1 (SD input) | VDDIO1 | -0.3~+4.2 | V |
| Supply voltage 2 (Control) | VDDIO2 | -0.3~+4.2 | V |
| Supply voltage 3 (HD output) | VDDIO3 | -0.3~+4.2 | V |
| Supply voltage 4 (PLL) | AVDD | -0.3~+4.2 | V |
| Supply voltage 5 (CORE) | VDD | -0.3~+1.68 | V |
| Input voltage 1 | VIN1 | -0.3~VDDIO1+0.3 | V |
| Input voltage 2 | VIN2 | -0.3~VDDIO2+0.3 | V |
| Input voltage 3 | VIN3 | -0.3~VDDIO3+0.3 | V |
| Storage temperature range | Tstg | -25~+125 | °C |
| Power dissipation | PD | 330*1, 1200*2 | mW |

*1 IC only. In the case exceeding 25°C, 3.3 mW should be reduced at the rating 1°C.

*2 When packaging a glass epoxy board of 114.3 × 76.2 × 1.6 mm. In the case exceeding 25°C, 12 mW should be reduced at the rating 1°C.

* Has not been designed to withstand radiation.

* Operation is not guaranteed.

● Operating Conditions

Table. 2 Operating conditions

| Parameter | Symbol | Min | Typ | Max | Unit |
|------------------------------|--------|------|-----|------|------|
| Supply voltage 1 (SD input) | VDDIO1 | 1.7 | 3.3 | 3.6 | V |
| Supply voltage 2 (Control) | VDDIO2 | 2.7 | 3.0 | 3.3 | V |
| Supply voltage 3 (HD output) | VDDIO3 | 1.7 | 1.8 | 1.9 | V |
| Supply voltage 4 (PLL) | AVDD | 2.7 | 3.0 | 3.3 | V |
| Supply voltage 5 (CORE) | VDD | 1.15 | 1.2 | 1.25 | V |
| Operating temperature range | Topr | -25 | - | 85 | °C |

● Electrical Characteristics (DC Characteristics)

Table. 3 Electric characteristics

| Parameter | Symbol | Specification | | | Unit | Conditions |
|----------------------------|-------------------|-----------------|------|-----------------|------|--|
| | | MIN | TYP | MAX | | |
| Operational current (CORE) | IDD1 | - | 150 | 200 | mA | When operated with HDCLK = 148.5 MHz |
| Operational current (IO) | IDD2 | - | 40 | 80 | mA | When operated with HDCLK = 148.5 MHz and external capacitor of 5pF |
| Operational current (CORE) | IDD3 | - | 15 | 20 | mA | When operated with DCLK = 27 MHz |
| Operational current (IO) | IDD4 | - | 10 | 20 | mA | When operated with HDCLK = 27 MHz and external capacitor of 5pF |
| Static current | IDDst | - | - | 800 | μA | In standby mode |
| Input "H" current | I _{IH} | -10 | - | 10 | μA | V _{IH} =VDDIO1/2 |
| Input "L" current | I _{IL} | -10 | - | 10 | μA | V _{IL} =GND |
| Input "H" voltage 1 | V _{IH1} | VDDIO1 *0.8 | - | VDDIO1 +0.3 | V | Ordinary input (Including input mode of I/O pin) |
| Input "L" voltage 1 | V _{IL1} | -0.3 | - | VDDIO1 *0.2 | V | Ordinary input (Including input mode of I/O pin) |
| Input "H" voltage 2 | V _{IH2} | VDDIO1 *0.85 | - | VDDIO1 +0.3 | V | Hysteresis input |
| Input "L" voltage 2 | V _{IL2} | -0.3 | - | VDDIO1 *0.15 | V | Hysteresis input |
| Hysteresis voltage range 2 | V _{hys2} | - | 0.75 | - | V | Hysteresis input |
| Output "H" voltage 1 | V _{OH1} | VDDIO2 -0.4 | - | VDDIO2 | V | I _{OH1} =-1.0mA(DC) SDOUT |
| Output "L" voltage 1 | V _{OL1} | 0.0 | - | 0.4 | V | I _{OL1} =1.0mA(DC) SDOUT |
| Output "H" voltage 2 | V _{OH2} | VDDIO3 -0.2 | - | VDDIO3 | V | I _{OH1} =-1.0mA(DC) HD output pin |
| Output "L" voltage 2 | V _{OL2} | 0.0 | - | 0.2 | V | I _{OL1} =1.0mA(DC) HD output pin |

(When not otherwise specified, under the conditions of VDD = 1.20 V, VDDIO1 = 3.3 V, VDDIO3 = 1.8 V, VDDIO2 = AVDD = 3.0 V, AVSS = GND = 0.0 V, and Ta = 25°C)

● Electrical Characteristics (AC Characteristics)

1. 3-wire serial interface timing

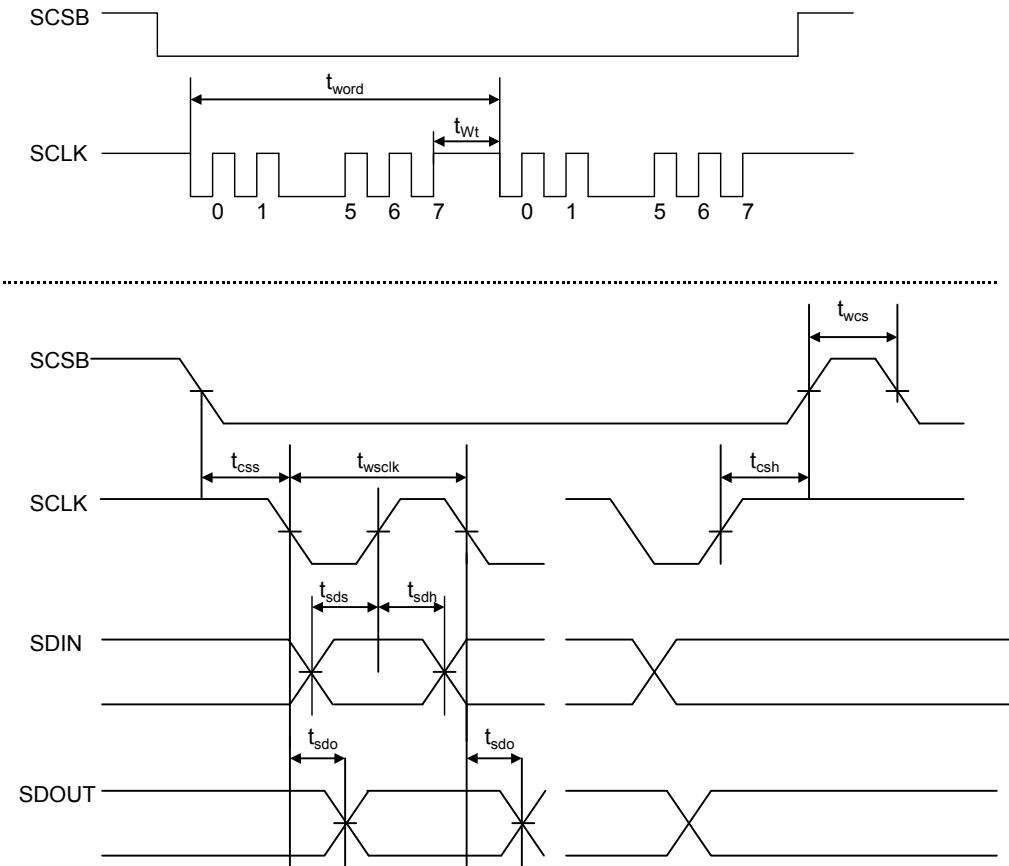


Fig. 1 3-wire serial interface format

Table. 4 3-wire serial interface format

| Symbol | Description | MIN | TYP | MAX | Unit |
|------------|---|-----|-----|-----|---------|
| t_{wclk} | SCLK clock cycle | 200 | - | - | ns |
| t_{wcs} | SCSB access interval | 1 | - | - | μ s |
| t_{css} | SCSB setup time | 200 | - | - | ns |
| t_{sds} | SDIN setup time | 30 | - | - | ns |
| t_{csh} | SCSB holding time | 1 | - | - | μ s |
| t_{sdh} | SDIN holding time | 30 | - | - | ns |
| t_{sdo} | Time from trailing of the clock to the establishment of SDOUT | - | - | 60 | ns |
| t_{word} | 1 word write time | 2.5 | - | - | μ s |
| t_{wt} | 1 word write interval | 1 | - | - | μ s |

2. Image Data Input Timing

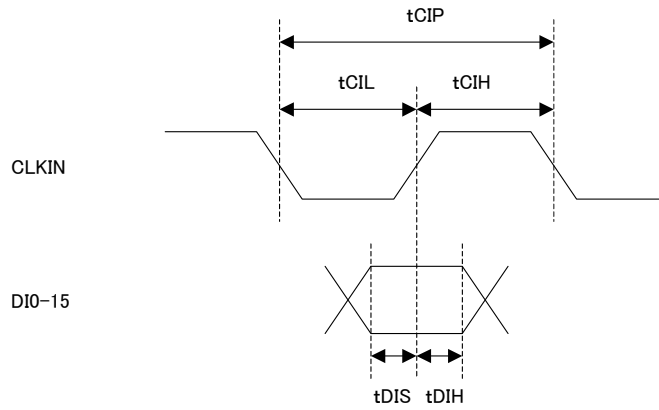


Fig. 2 Image Data Input Timing

Table. 5 Image Data Input Timing

| Symbol | Description | MIN | TYP | MAX | Unit |
|-----------|---|-----|-------|-----|------|
| t_{CIP} | CLKIN Clock cycle | - | 37.03 | - | ns |
| d_{CKI} | CLKIN clock duty (t_{CIL}/t_{CIP} or t_{CIH}/t_{CIP}) | 45 | 50 | 55 | % |
| t_{DIS} | Data setup time from the CLKIN rise | 2 | - | - | ns |
| t_{DIH} | Data holding time from the CLKIN rise | 3 | - | - | ns |

3. Image Data Output Timing

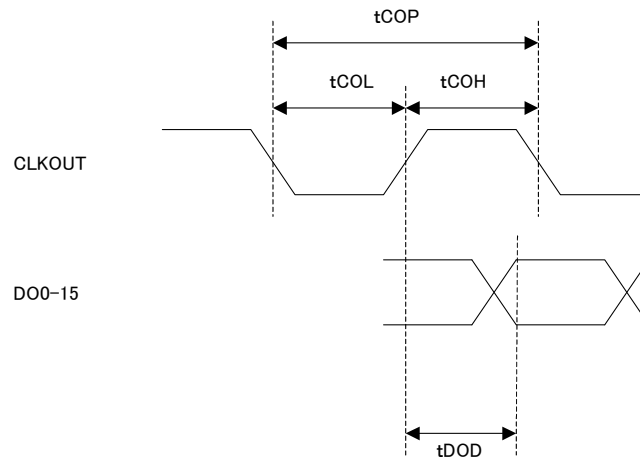


Fig. 3 Image Data Output Timing

Table. 6 Image Data Output Timing

| Symbol | Description | MIN | TYP | MAX | Unit |
|-----------|--|-------|-----|-------|------|
| t_{COP} | CLKOUT Clock cycle | 6.734 | - | - | ns |
| d_{CKO} | CLKOUT clock duty (t_{COL}/t_{COP} or t_{COH}/t_{COP}) * | 45 | - | 55 | % |
| t_{DOD} | Time from the rise of CLKOUT to the establishment of DO0-15 | 1 | - | 12 | ns |
| t_{DOD} | Time from the rise of CLKOUT to the establishment of DO0-15 | 1 | - | 5.734 | ns |
| t_{JIT} | Output jitter of CLKOUT (1 us cycle) | - | - | 2 | ns |

* When PLL is used. When 27 MHz is output, the input clock duty is 50%.

● Pin configuration diagram (Bottom View)

Fig. 4 Pin configuration diagram of BU1521GVW (Bottom view).

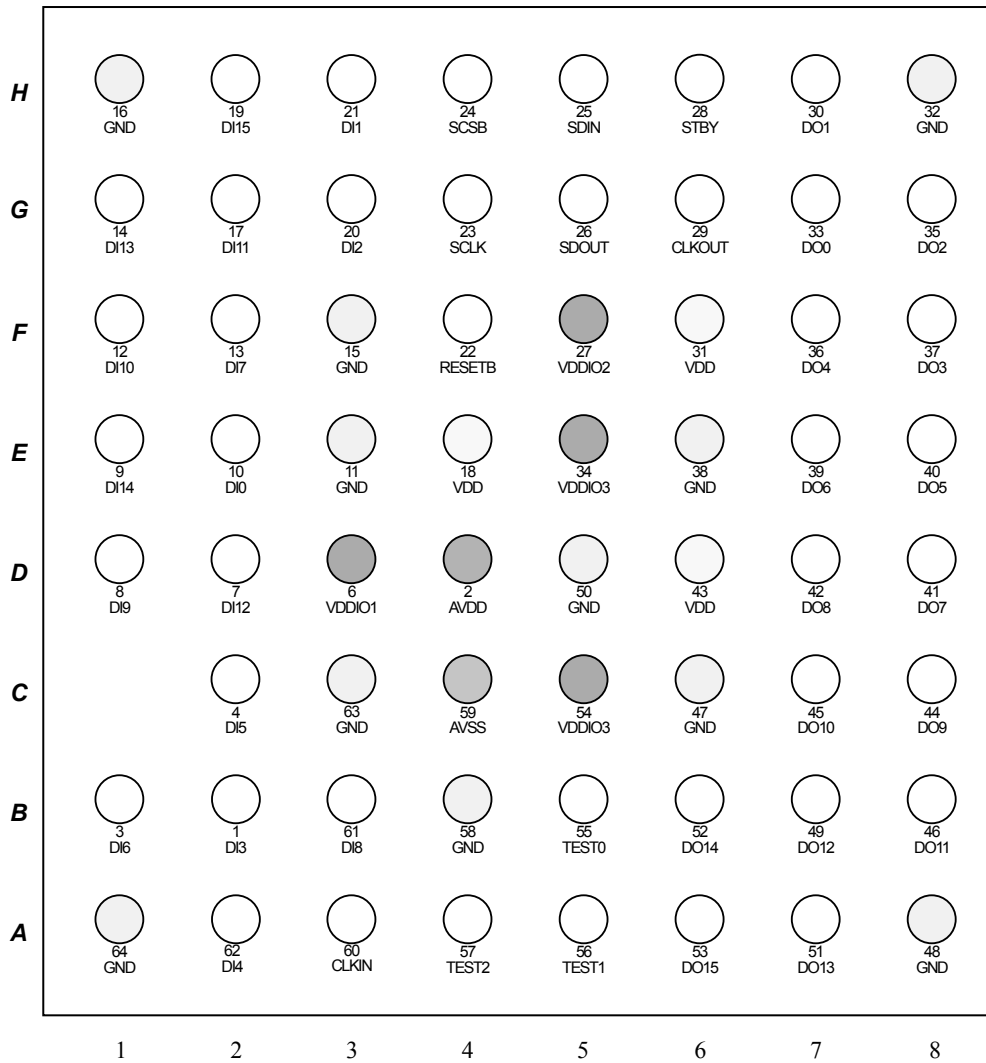


Fig. 4 BU1521GVW Pin configuration diagram(Bottom View)

● Pin Function

Table. 7 BU1521GVW terminal function(1)

| PIN No. | Ball No. | PIN Name | In/Out | Init | Function Description | I/O Type | I/O System |
|---------|----------|----------|--------|------|---|----------|------------|
| 1 | B2 | DI3 | In | – | 3rd bit of SD input data | B | VDDIO1 |
| 2 | D4 | AVDD | – | – | Power Source for PLL | – | – |
| 3 | B1 | DI6 | In | – | 6th bit of SD input data | B | VDDIO1 |
| 4 | C2 | DI5 | In | – | 5th bit of SD input data | B | VDDIO1 |
| 5 | – | N.C *1 | – | – | – | – | – |
| 6 | D3 | VDDIO1 | – | – | Data input IO voltage (Typical 3.3 V) | – | – |
| 7 | D2 | DI12 | In | – | 12th bit of SD input data | B | VDDIO1 |
| 8 | D1 | DI9 | In | – | 9th bit of SD input data | B | VDDIO1 |
| 9 | E1 | DI14 | In | – | 14th bit of SD input data | B | VDDIO1 |
| 10 | E2 | DI0 | In | – | 0th bit of SD input data | B | VDDIO1 |
| 11 | E3 | GND | – | – | GND | – | – |
| 12 | F1 | DI10 | In | – | 10th bit of SD input data | B | VDDIO1 |
| 13 | F2 | DI7 | In | – | 7th bit of SD input data | B | VDDIO1 |
| 14 | G1 | DI13 | In | – | 13th bit of SD input data | B | VDDIO1 |
| 15 | F3 | GND | – | – | GND | – | – |
| 16 | H1 | GND | – | – | GND | – | – |
| 17 | G2 | DI11 | In | – | 11th bit of SD input data | B | VDDIO1 |
| 18 | E4 | VDD | – | – | Core power supply (1.2 V) | – | – |
| 19 | H2 | DI15 | In | – | 15th bit of SD input data | B | VDDIO1 |
| 20 | G3 | DI2 | In | – | 2nd bit of SD input data | B | VDDIO1 |
| 21 | H3 | DI1 | In | – | 1st bit of SD input data | B | VDDIO1 |
| 22 | F4 | RESETB | In | – | Reset pin (low active) | B*2 | VDDIO2 |
| 23 | G4 | SCLK | In | – | 3-wire serial I/F clock | B*2 | VDDIO2 |
| 24 | H4 | SCSB | In | – | 3-wire serial I/F chip select | B*2 | VDDIO2 |
| 25 | H5 | SDIN | In | – | 3-wire serial I/F data input | B*2 | VDDIO2 |
| 26 | G5 | SDOUT | Out | Low | 3-wire serial I/F data output | C*3 | VDDIO2 |
| 27 | F5 | VDDIO2 | – | – | Control signal IO voltage (typically 3.3 V) | – | – |
| 28 | H6 | STBY | In | – | IC stand-by control | A | VDDIO2 |
| 29 | G6 | CLKOUT | Out | Low | HD clock output | D | VDDIO3 |
| 30 | H7 | DO1 | Out | PD | 1st bit of HD output pin | C | VDDIO3 |
| 31 | F6 | VDD | – | – | Core power supply (1.2 V) | – | – |
| 32 | H8 | GND | – | – | GND | – | – |
| 33 | G7 | DO0 | Out | PD | 0th bit of HD output pin | C | VDDIO3 |
| 34 | E5 | VDDIO3 | – | – | Data output IO voltage (typically 1.8 V) | – | – |
| 35 | G8 | DO2 | Out | PD | 2nd bit of HD output pin | C | VDDIO3 |
| 36 | F7 | DO4 | Out | PD | 4th bit of HD output pin | C | VDDIO3 |
| 37 | F8 | DO3 | Out | PD | 3rd bit of HD output pin | C | VDDIO3 |
| 38 | E6 | GND | – | – | GND | – | – |
| 39 | E7 | DO6 | Out | PD | 6th bit of HD output pin | C | VDDIO3 |
| 40 | E8 | DO5 | Out | PD | 5th bit of HD output pin | C | VDDIO3 |
| 41 | D8 | DO7 | Out | PD | 7th bit of HD output pin | C | VDDIO3 |

Table. 8 BU1521GVW terminal function(2)

| PIN No. | Ball No. | PIN Name | In/Out | Init | Function Description | I/O Type | I/O System |
|---------|----------|----------|--------|------|--|----------|------------|
| 42 | D7 | DO8 | Out | PD | 8th bit of HD output pin | C | VDDIO3 |
| 43 | D6 | VDD | – | – | Core power supply (1.2 V) | – | – |
| 44 | C8 | DO9 | Out | PD | 9th bit of HD output pin | C | VDDIO3 |
| 45 | C7 | DO10 | Out | PD | 10th bit of HD output pin | C | VDDIO3 |
| 46 | B8 | DO11 | Out | PD | 11th bit of HD output pin | C | VDDIO3 |
| 47 | C6 | GND | – | – | GND | – | – |
| 48 | A8 | GND | – | – | GND | – | – |
| 49 | B7 | DO12 | Out | PD | 12th bit of HD output pin | C | VDDIO3 |
| 50 | D5 | GND | – | – | GND | – | – |
| 51 | A7 | DO13 | Out | PD | 13th bit of HD output pin | C | VDDIO3 |
| 52 | B6 | DO14 | Out | PD | 14th bit of HD output pin | C | VDDIO3 |
| 53 | A6 | DO15 | Out | PD | 15th bit of HD output pin | C | VDDIO3 |
| 54 | C5 | VDDIO3 | – | – | Data output IO voltage (Typical 1.8 V) | – | – |
| 55 | B5 | TEST0 | In | – | Test pin 0 (Connect to GND) | A | VDDIO3 |
| 56 | A5 | TEST1 | In | – | Test pin 1 (Connect to GND) | A | VDDIO3 |
| 57 | A4 | TEST2 | In | – | Test pin 2 (Connect to GND) | A | VDDIO3 |
| 58 | B4 | GND | – | – | GND | – | – |
| 59 | C4 | AVSS | – | – | GND for PLL | – | – |
| 60 | A3 | CLKIN | In | – | SD clock input (27 MHz) | B | VDDIO1 |
| 61 | B3 | DI8 | In | – | 8th bit of SD input data | B | VDDIO1 |
| 62 | A2 | DI4 | In | – | 4th bit of SD input data | B | VDDIO1 |
| 63 | C3 | GND | – | – | GND | – | – |
| 64 | A1 | GND | – | – | GND | – | – |

Init column indicates pin status when released from reset. Low: L output PD: Pull-down
 *1: No balls *2: Input suspend function is fixed to OFF by an internal signal *3: No pull-down function

● Block Diagram

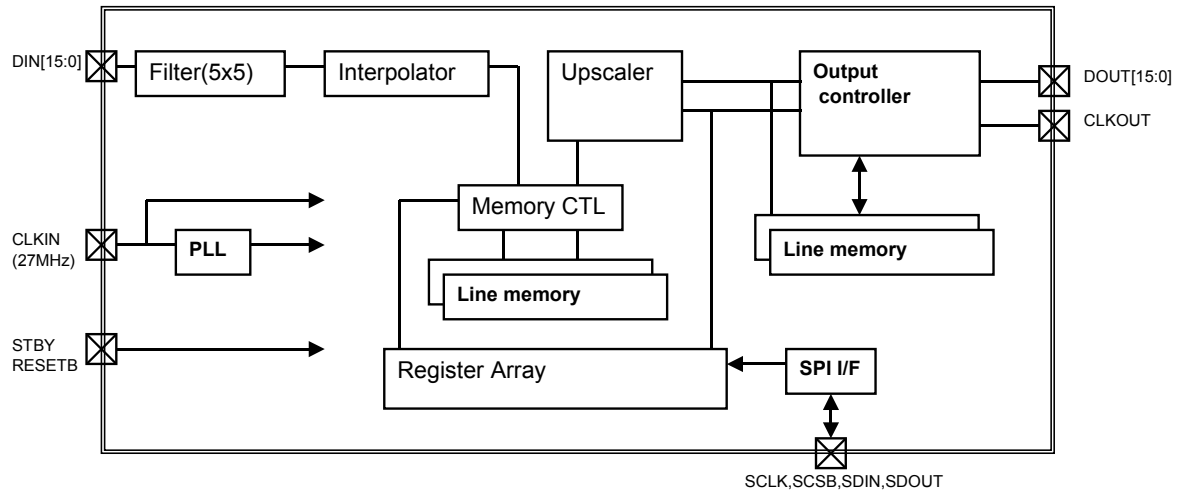


Fig. 5 BU1521GVW Block diagram

● Functions Discription

1. Input format

The following is the input format for BU1521GVW

480i or 576i(ITUR BT656) YCbCr 4:2:2 8bit(ITUR BT601) Digital Interface

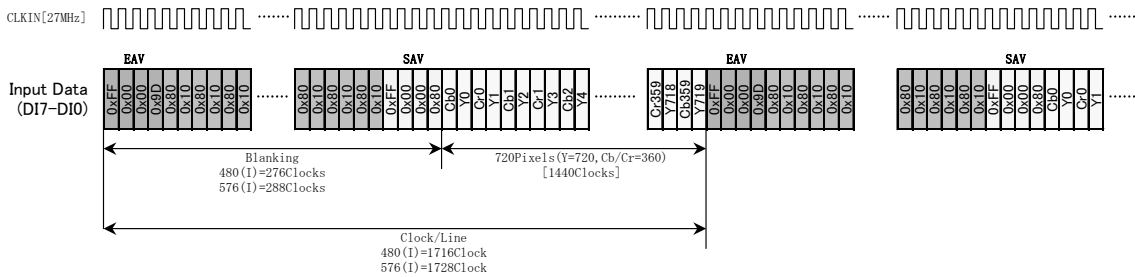
Table. 9 Input format

| Format | Data bit width | Pixel clock (MHz) | Size including blank (HxV) | Active Size (HxV) | Standard |
|------------|----------------|-------------------|----------------------------|-------------------|--------------|
| 480/59.94i | 8 | 27 | 858x525 | 720x(244/243) | ITUR BT656-4 |
| 576/50i | 8 | 27 | 864x625 | 720x(288/288) | |

SYS2 register (0 × 12) setting allows applying whether Y data and CbCr data to be assigned to lower DI [7:0] or upper DI [15:8].

2. Output format

480 (I), 576 (I)



The following is the output format for BU1521GVW:

- 480i or 576i(ITUR BT656) YCbCr 4:2:2 8bit (ITUR BT601)Digital Interface
- 480p or 576p(ITUR BT1358) YCbCr 4:2:2 16bit(ITUR BT601) Digital Interface
- 1080/59.94i(SMPTE 274) YCbCr 4:2:2 16bit(ITUR BT601) Digital Interface
- 1080/50i(SMPTE 274) YCbCr 4:2:2 16bit(ITUR BT601) Digital Interface
- 1080/59.94p(SMPTE 274) YCbCr 4:2:2 16bit(ITUR BT601) Digital Interface
- 1080/50p(SMPTE 274) YCbCr 4:2:2 16bit(ITUR BT601) Digital Interface

Table. 10 Output format

| Format | Data bit width | Pixel Clock Frequency (MHz) | Blanking Size including Line (HxV) | Active Image Size (HxV) | Standard |
|-------------|----------------|-----------------------------|------------------------------------|-------------------------|---------------------------|
| 480/59.94i | 8 | 27 | 858x525 | 720x(244/243) | ITUR BT656-4 |
| 576/50i | 8 | 27 | 864x625 | 720x(288/288) | |
| 480/59.94p | 16 | 27 | 858x525 | 720x483 | ITUR BT1358 SMPTE 293M |
| 576/50p | 16 | 27 | 864x625 | 720x576 | |
| 1080/59.94i | 16 | 74.25/1.001 | 2200x1125 | 1920x1080 | SMPTE 274 |
| 1080/50i | 16 | 74.25 | 2640x1125 | 1920x1080 | |
| 1080/59.94p | 16 | 148.5/1.001 | 2200x1125 | 1920x1080 | |
| 1080/50p | 16 | 148.5 | 2640x1125 | 1920x1080 | |

3. IP conversion, upscale function

BU1521GVW upscales and interpolates images when upconverting to output format.

Supported image data I/O conversion is shown in Table. 11 .

Only input size of 720 or upscale to 1920 are supported for the horizontal direction.

The edge of the upscaled image can be enhanced (3 levels) by changing the UPC_SEL register.

When upscaling the 480i input, upscaling is applied to 240 lines among the overall effective lines

Table. 11 Image data I/O conversion table

| Input (SD) | Output (HD) | | | | | | | |
|------------|----------------|----------------|-------------|-------------|-----------------|--------------|-----------------|--------------|
| | 480/ 59.94i | 480/ 59.94p | 576/ 50i | 576/ 50p | 1080/ 59.94i | 1080/ 50i | 1080/ 59.94p | 1080/ 50p |
| 480/59.94i | ○ | ○※ | — | — | ○ | — | ○ | — |
| 576/50i | — | — | ○ | ○ | — | ○ | — | ○ |

* Immediately after reset and when standby mode is set, 480i becomes 480p.

4. Filter function

BU1521GVW can apply 5 taps of filtering both horizontally and vertically.

5 taps of filter tap coefficients can be set independently on horizontal and vertical directions using filter coefficient registers (0x14–0x1B).

5 x 5 Filter tap coefficients = Horizontal filter tap coefficients x Vertical filter tap coefficients.

The values of the horizontal and vertical filter taps must be set to make the sum of the coefficients 64.

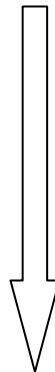
The initial value makes the filter invalid.

[Horizontal filter tap coefficients]

| | | | | | |
|-----|-----|-----|-----|-----|-----|
| 1 | 2 | 3 | 4 | 5 | /64 |
| TH1 | TH2 | TH3 | TH4 | TH5 | |

[Vertical filter tap coefficients]

| | | |
|---|-----|-----|
| 1 | TV1 | /64 |
| 2 | TV2 | |
| 3 | TV3 | |
| 4 | TV4 | |
| 5 | TV5 | |



[5 x 5 filter tap coefficients]

| 行番号 | 列番号 | | | | |
|-----|---------|---------|---------|---------|---------|
| | 1 | 2 | 3 | 4 | 5 |
| 1 | TH1*TV1 | TH2*TV1 | TH3*TV1 | TH4*TV1 | TH5*TV1 |
| 2 | TH1*TV2 | TH2*TV2 | TH3*TV2 | TH4*TV2 | TH5*TV2 |
| 3 | TH1*TV3 | TH2*TV3 | TH3*TV3 | TH4*TV3 | TH5*TV3 |
| 4 | TH1*TV4 | TH2*TV4 | TH3*TV4 | TH4*TV4 | TH5*TV4 |
| 5 | TH1*TV5 | TH2*TV5 | TH3*TV5 | TH4*TV5 | TH5*TV5 |

Fig. 6 5 x 5 filter tap coefficients

5. Register access

Registers are accessed by 3 wire serial interfaces (SCSB, SCLK, SDIN, SDOUT).

Burst write/read is supported; therefore, consecutive writing is possible.

◆ Regular write sequence

The address 8 bits and data 8 bits should be written in this order.

Both address and data have MSB first.

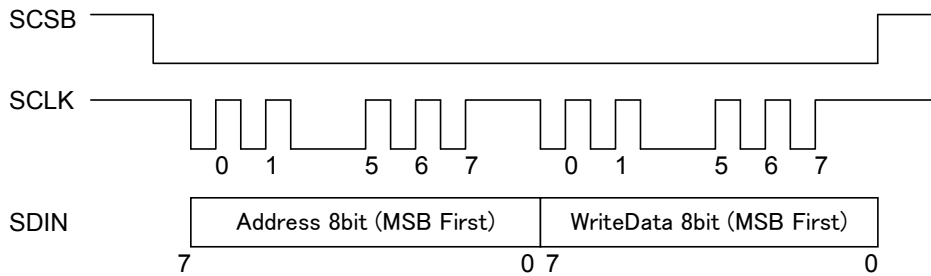


Fig. 7 Regular write sequence

◆ Regular read sequence

For reading, the address of the register to be read out should be written in the SADR register (0 × 70), then SRDAT register (0 × 80) should be read out. Both address and data have MSB first.

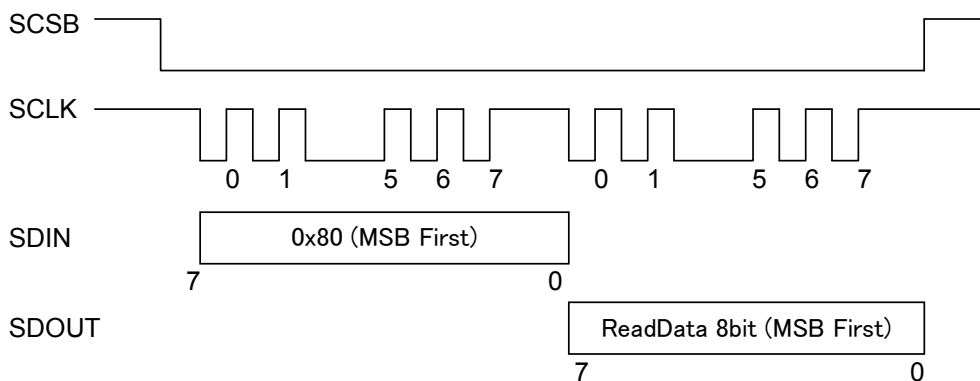


Fig. 8 Regular read sequence

6. PLL

BU1521GVW has an integrated PLL to generate and output the clock for HD format from the 27 MHz pixel clock.

The PLL output frequency is selected and output is executed according to the output format only, by setting the output format to the register.

The input frequency is 27 MHz and the output frequency can be 74.25 MHz, 74.25/1.001 MHz, 148.5 MHz, or 148.5/1.001 MHz.

With 480i/576i output format, the 27 MHz input clock is output without going through the PLL.

● I/O pin equivalent circuit diagram

Fig. 10 An I/O pin equivalent circuit diagram.

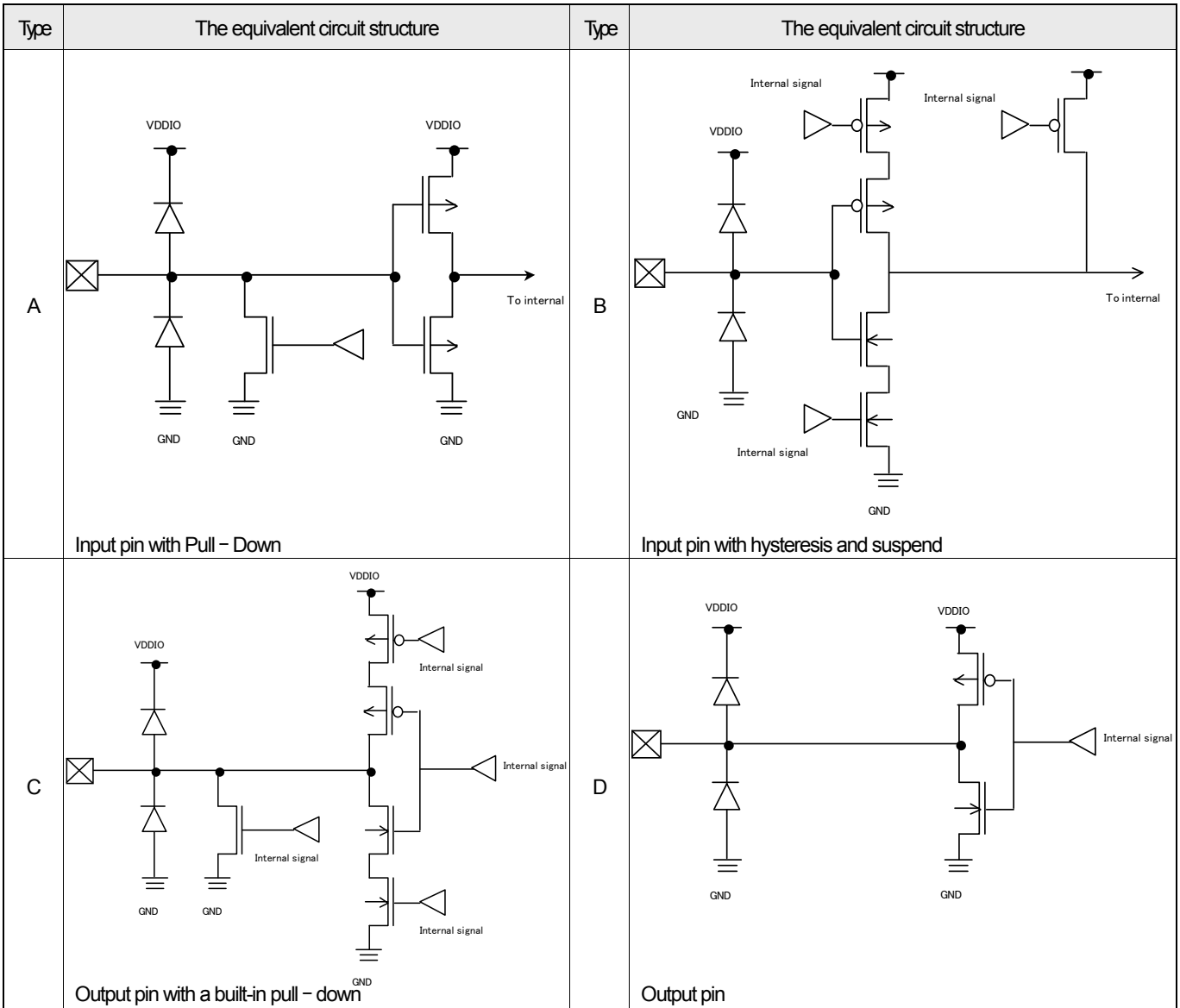


Fig. 10 BU1521GVW I/O pin equivalent circuit diagram

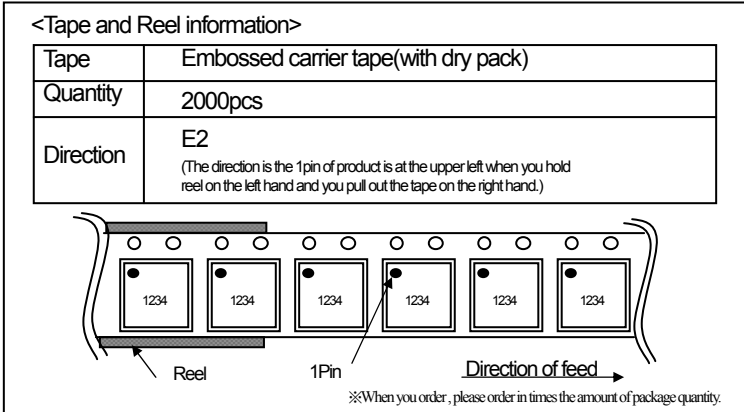
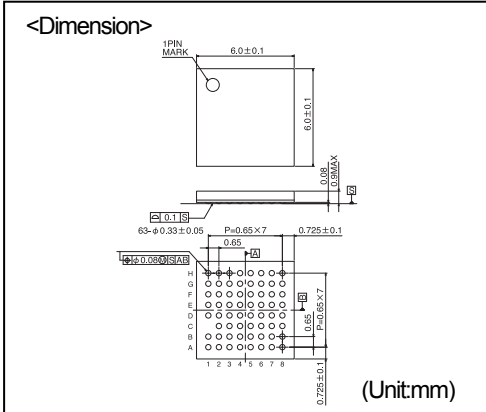
● Not for uses

- (1) Absolute Maximum Ratings
An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.
- (2) Operating conditions
These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.
- (3) Reverse connection of power supply connector
The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.
- (4) Power supply line
Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines.
In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.
Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.
- (5) GND voltage
Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.
- (6) Short circuit between terminals and erroneous mounting
In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.
- (7) Operation in strong electromagnetic field
Be noted that using ICs in the strong electromagnetic field can malfunction them.
- (8) Inspection with set PCB
On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.
- (9) Input terminals
In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.
- (10) Ground wiring pattern
If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.
- (11) External capacitor
In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

● Ordering part number

| | | | | | | | | | | |
|--------------------|---|----------|---|---|---|----------------------|---|---|---|---|
| B | U | 1 | 5 | 2 | 1 | G | V | W | E | 2 |
| ROHM model name | | Part No. | | | | Package GVW: SBGA | | | Packaging and forming specification E2: Embossed tape and reel | |

SBGA063W060



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